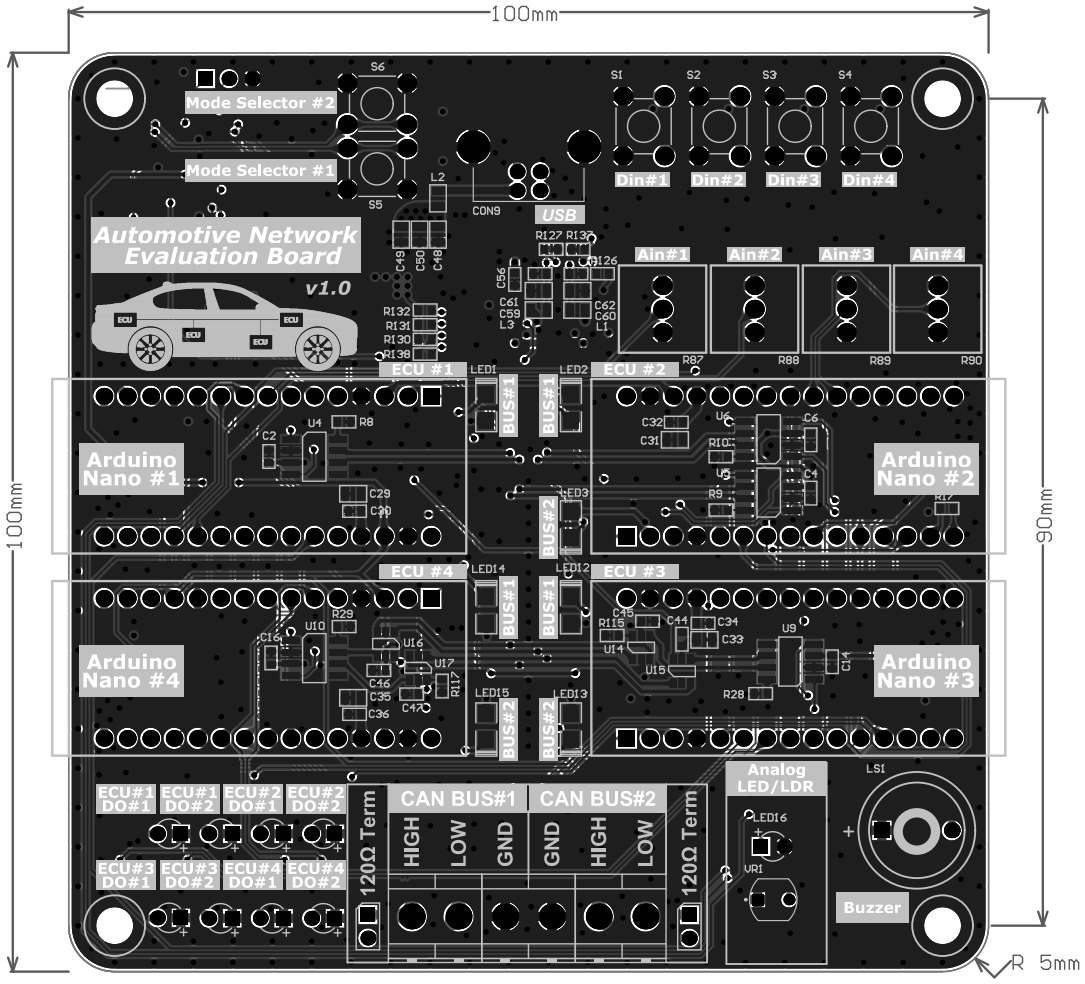

PCB SPECIFICATIONS

MATERIAL: FR4 Fiberglass: 1.6mm +/− 10%
Prepegs per IPC4101

LAYERS: Multilayer PCB: Four Layers;

PCB Finishing:

☒ HASL (Hot Air Solder Leveling) − IPC−A−600;

☐ ENIG (Electroless nickel immersion gold):
3.0~6.0 um (Ni) + 0.05 [MIN] um (Au) − IPC−4552.

SOLDER MASK: GREEN

SILKSCREEN:

☒ Top Overlay ☒ Bottom Overlay

COLOR: WHITE

VIA FINISHING:

☒ Tenting ☐ Button ☐ Plugged

NOTES (UNLESS OTHERWISE SPECIFIED):

1 − Dimensions in millimeters. Tolerance: +/− 0.2 mm;
2 − Maximum bending and torsion: 1%;
3 − PCB Electrical Testing needed;
4 − Use the files sent with the documentation for the drilling process;
5 − Follow MANDATORILY the stack−up and the copper's (Cu) thickness indicated in the LAYER STACK TABLE;
6 − Follow the standard IPC−A−600 Class 2
7 − Use the indicated area on Top Overlay for the insertion of the PCB manufacturer's logo and other information.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.035mm		
4	Dielectric 1	FR-4	0.180mm	4.2	
5	Ground Plane	Copper	0.035mm		
6	Dielectric 3		1.080mm	4.2	
7	Signal/Power	Copper	0.035mm		
8	Dielectric 2		0.180mm	4.2	
9	Bottom Layer	Copper	0.035mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				